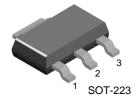


September 2006

# FJT44 **NPN Epitaxial Silicon Transistor**

· High Voltage Transistor



1. Base 2. Collector 3. Emitter

## Absolute Maximum Ratings\* Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	500	V
V <sub>CEO</sub>	Collector-Emitter Voltage	400	V
V <sub>EBO</sub>	Emitter-Base Voltage	6	V
I <sub>C</sub>	Collector Current	300	mA
P <sub>C</sub>	Collector Dissipation (Ta = 25 °C)	2	W
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature Range	- 55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### Thermal Characteristics\* Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm. mounting pad for the collector lead min. 6 cm <sup>2</sup>

## Electrical Characteristics\* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	I <sub>C</sub> = 100uA, I <sub>E</sub> = 0	500			V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	$I_{C} = 1 \text{mA}, I_{B} = 0$	400			V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 100 \mu A, I_C = 0$	6			V
I <sub>CBO</sub>	Collector-Base Cutoff Current	V <sub>CB</sub> = 400V I <sub>E</sub> = 0			100	nA
I <sub>CES</sub>	Collector-Emitter Cutoff Current	V <sub>CE</sub> = 400V, V <sub>BE</sub> = 0			500	nA
I <sub>EBO</sub>	Emitter-Base Cutoff Current	$V_{CE} = 4V$ , $I_C = 0$			100	nA
h <sub>FE</sub>	DC Current Gain	V <sub>CE</sub> =10V, I <sub>C</sub> =1mA V <sub>CE</sub> =10V, I <sub>C</sub> =10mA V <sub>CE</sub> =10V, I <sub>C</sub> =50mA V <sub>CE</sub> =10V, I <sub>C</sub> =100mA	40 50 45 40		200	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$\begin{split} I_C &= 1\text{mA},\ I_B = 0.1\text{mA} \\ I_C &= 10\text{mA},\ I_B = 1\text{mA} \\ I_C &= 50\text{mA},\ I_B = 5\text{mA} \end{split}$			0.4 0.5 0.75	V V V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1mA			0.75	V
C <sub>obo</sub>	Output Capacitance	$V_{CB} = 20V, I_{E} = 0, f = 1MHz$			7	pF

<sup>\*</sup> Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

<sup>1)</sup> These ratings are based on a maximum junction temperature of 150°C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Typical Performance Characteristics**

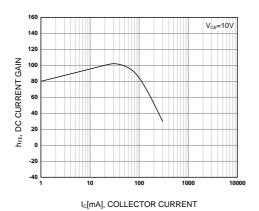


Figure 1. DC current Gain

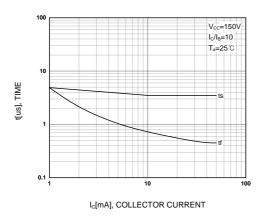


Figure 3. Turn-Off Switching Times

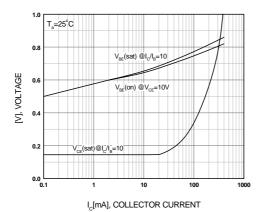


Figure 5. On Voltage

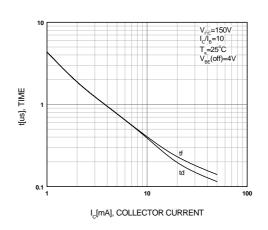


Figure 2. Turn-On Switching Times

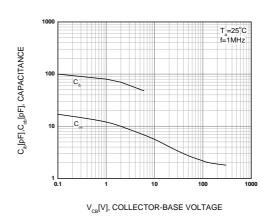


Figure 4. Capacitance

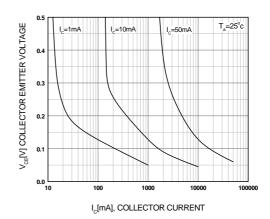


Figure 6. Collector Saturation Region

# **Typical Performance Characteristics**

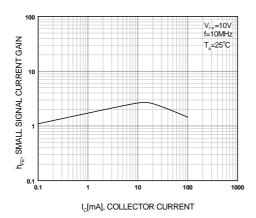
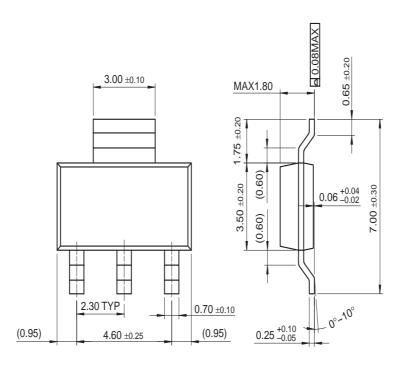
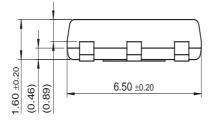


Figure 1. High Frequency Current Gain

## **Mechanical Dimensions**

# **SOT-223**





Dimensions in Millimeters

UltraFET® UniFET™ VCX™ Wire™

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Across the board. Aroun The Power Franchise <sup>®</sup>	id the world.™	μSerDes™ ScalarPump™	TruTranslation™ UHC™
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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